# Trigger-Output Event-Driven SOI pixel sensor for X-ray Astronomy

Takeshi Tsuru<sup>1</sup> on behalf of the X-ray SOIPIX collaboration<sup>2</sup> 1 Department of Physics, Faculty of Science, Kyoto University Kitashirakawa-Oiwake-Cho, Kyoto, 606-8502 Japan E-mail: tsuru@cr.scphys.kyoto-u.ac.jp

**Abstract** We are developing monolithic active pixel sensors, called X-ray SOIPIXs. These sensors are based on a Silicon-On-Insulator (SOI) CMOS technology and are intended for use on future X-ray astronomy satellites (e.g., Tsuru+18, Proc. SPIE, 10709, doi: 10.1117/12.2312098). Each pixel has an event trigger output function which allows for an immediate readout of only the pixels hit by an X-ray with its high time resolution better than ~10  $\mu$ s. This paper presents the introduction of the X-ray SOIPIX and its current achievements.

Keywords: SOI pixel sensor, X-ray, imaging, spectroscopy

#### 1. X-ray Astronomy

X-ray astronomy is the study of celestial objects at X-ray wavelengths. Since X-rays from celestial objects are absorbed by the atmosphere, it is necessary to develop satellites equipped with X-ray instruments to observe celestial objects. The current standard X-ray instruments are imaging spectroscopy systems combining a Wolter-I type X-ray telescope and an X-ray CCD imager [1]. We operate the X-ray CCD in single photon counting mode to obtain the position on the CCD (direction of arrival), energy and arrival times of each incident X-ray.

#### 2. Limitation of X-ray CCD

X-ray CCDs have high performance in terms of imaging and spectroscopy [2, 3]. However, the current time resolution of Xray CCDs cannot keep up with the improved performance of Xray telescopes. As the X-ray collecting area of the telescope increases and the angular resolution improves, the probability of multiple X-ray photons hitting the same pixel during single exposure increases, making it impossible to measure the X-ray energy (pile-up). Also, fast time variability, such as black holes, cannot be observed. High temporal resolution and fast readout are therefore required for the next generation of X-ray imagers.

#### 3. Trigger-Output Event-Driven SOI pixel sensor

We are developing a Trigger-Output Event-Driven SOI pixel sensor (X-ray SOIPIX) for the next generation of X-ray imager [4]. An SOI pixel sensor is monolithic using bonded wafer of high resistivity depleted Si layers for X-ray detection, SiO2 insulator and low resistivity Si for CMOS circuits [5, 6]. In the X-ray SOIPIX, each pixel has an event trigger output function that allows immediate readout of only those pixels hit by an X-ray with its high time resolution better than ~10  $\mu$ s. Bulk CMOS image sensors can also be equipped with the function. However, the depletion thickness of bulk CMOS image sensors is too thin to detect high energy X-rays. Then, we adopt SOI pixel sensor technology.

Since 2010, we have been developing X-ray SOIPIXs using Lapis Semiconductor's 0.2  $\mu$ m FD-SOI CMOS technology [7]. The development of the sensor focuses on three main aspects: pixel circuits, device structures and on-chip functions.

#### 4. Pixel circuit and Device Structure

A pixel circuit consists of an analog readout circuit and a comparator circuit. The analog readout circuit consists of a charge sensitive amplifier, CDS sampling, source follower. We use an inverter chopper type comparator.

The device structure was the most challenging part of the development. A small capacitance at the readout node is required to reduce the readout noise. The back gate effect of the circuit due to the electric field from the back bias is needs to be avoided [6]. The dark current from the interface between the sensor layer and the BOX layer needs to be reduced.

Interference between the readout node and the circuit is necessary to be avoided. Signal charges generated at the pixel boundaries are required to also be collected without loss [8, 9]. Together with the Kawahito group at Shizuoka University, we have successfully developed a PDD (Pinned Depleted Diode) structure to meet this requirement [10, 11, 12].

#### 5. Performances

From the above developments, the required performance has now been achieved: observations with a temporal resolution better than 10  $\mu$ s at an event rate higher than ~500 Hz can be made without pile-up. The quantum efficiency already meets the requirements for the high energy band above 6 keV, which is determined by the depletion layer thickness [13]. The one in the low energy band below 1 keV still has room for improvement. We will develop it in the future. Energy resolution is the most difficult performance item, but the requirements are met [11, 13, 14]. However, there is still room for performance improvement. This will also be developed in the future. In terms of radiation resistance, the probability of the SEU is very low thanks to its SOI structure [15], and the TID has also been experimentally proven to meet the required performance over the observation period [16, 17].

#### 6. On-chip function and "Digital X-ray SOIPIX"

We are developing various on-chip functions to increase practicality and broaden the range of applications. One is onchip pattern processing and particle species identification [18]. X-rays produce compact clouds of signal charges, while highenergy charged particles produce tracks. Using this property, we have implemented an on-chip function to discriminate between the two.

On-chip ADCs, DACs, and BGRs (bandgap reference) are also being developed: a 14-bit 1-stage cyclic ADC and a 12-bit DAC have been developed, and test devices have been processed. Imaging spectroscopy using the ADCs has been successfully performed [19]. We are now developing a function to generate the clock to drive the sensor to simplify the interface and readout circuitry.

#### 7. Applications other than X-ray astronomy

We are implementing scientific applications of the X-ray SOIPIX. We are developing the electron-track Compton gamma-ray camera [20, 21, 22], preparing a solar axion search experiment [23], a Lunar and planetary X-ray fluorescence mapping camera, and neutron TOF imaging spectroscopy.

The X-ray SOIPIX collaboration: M.Nobukawa (Nara Edu.), Y.Uchida, Y.Sbhimizu, F.Shiga, S.Fujita, T.Kohmura (Tokyo Sci.), K.Shimazoe, S.Sato, H.Matsuhashi, K.Hagino, Y.Onuki, K.Nagai (Tokyo), M.Uenomachi (Tokyo I. Tech.), H.Odaka (Osaka), M.Kagaya (Sendai Nct.), R.Azuma, N.Terano, T.Tanaka (Konan), Y.Fukazawa, M.Hashizume, Y.Suda (Hiroshima), T.Kishimoto, K.Nobukawa, Y.Nishimura, S.Kuwano, R.Matsui (Kindai), M.Matsuda, T.Narita, H.Uchida, Y.Komura, H.Uebayashi, T.Tsuru (Kyoto), K.Mori, Y.Fuchita, M.Indo, K.Kadoya, S.Kamada, E.Kurogi, M.Kimura, H.Mitani, S.Nagayama, Y.Nishioka, Y.Saito, Y.Sasaki, N.Shigematsu, A.Shiokawa, K.Sugimoto, R.Takagi, A.Takeda, T.Tanaka, T.Sakamoto, T.Yoshida, M.Yukumoto (Miyazaki), H.Nakajima (Kanto Gakuin), H.Katagiri (Ibaraki), Y.Arai, T.Ikeda, T.Takayanagi (KEK), H.Suzuki (ISAS), I.Kurachi (D&S)

#### References

- Koyama, K. *et al.* X-Ray Imaging Spectrometer (XIS) on Board Suzaku. *Publications of the Astronomical Society of Japan* 59, S23–S33 (2007).
- [2] Tanaka, T. et al. Soft X-ray Imager aboard Hitomi (ASTRO-H). JATIS 4, 011211 (2018).
- [3] Mori, K. et al. Status of Xtend telescope onboard X-Ray Imaging and Spectroscopy Mission (XRISM). Space Telesc. Instrum. 2024: Ultrav. Gamma Ray 54 (2024) doi:10.1117/12.3019804.
- [4] Tsuru, T. G. et al. Kyoto's event-driven x-ray astronomy SOI pixel sensor for the FORCE mission. in *High Energy*, *Optical, and Infrared Detectors for Astronomy VIII* (eds. Holland, A. D. & Beletic, J.) vol. 10709 107090H (High Energy, Optical, and Infrared Detectors for Astronomy VIII, 2018).
- [5] Arai, Y. et al. Developments of SOI monolithic pixel detectors. Nuclear Instruments and Methods in Physics Research Section A: Accelerators, Spectrometers, Detectors and Associated Equipment 623, 186–188 (2010).
- [6] Arai, Y. et al. Development of SOI pixel process technology. Nuclear Instruments and Methods in Physics Research Section A: Accelerators, Spectrometers, Detectors and Associated Equipment 636, S31–S36 (2011).
- [7] Ryu, S. G. *et al.* First Performance Evaluation of an X-Ray SOI Pixel Sensor for Imaging Spectroscopy and Intra-Pixel Trigger. *IEEE Trans. Nucl. Sci.* 58, 2528–2536 (2011).
- [8] Negishi, K. *et al.* X-ray response evaluation in subpixel level for X-ray SOI pixel detectors. *NIMA* **924**, 462–467 (2019).
- [9] Kayama, K. *et al.* Subpixel response of SOI pixel sensor for X-ray astronomy with pinned depleted diode: first result from mesh experiment. *JINST* 14, C06005–C06005 (2019).
- [10] Kamehama, H. *et al.* A Low-Noise X-ray Astronomical Silicon-On-Insulator Pixel Detector Using a Pinned Depleted Diode Structure. *Sensors* 18, 27 (2018).
- [11] Yukumoto, M. et al. Design study and spectroscopic performance of SOI pixel detector with a pinned depleted diode structure for X-ray astronomy. Nucl. Instrum. Methods Phys. Res. Sect. A: Accel., Spectrometers, Detect. Assoc. Equip. 1060, 169033 (2024).
- [12] Hagino, K. et al. Radiation-Induced Degradation Mechanism of X-Ray SOI Pixel Sensors With Pinned Depleted Diode Structure. *IEEE Trans. Nucl. Sci.* 70, 1444–1450 (2023).
- [13] Kodama, R. *et al.* Low-energy X-ray performance of SOI pixel sensors for astronomy, "XRPIX". *NIMA* 986, 164745 (2021).

- [14] Harada, S. *et al.* Performance of the Silicon-On-Insulator pixel sensor for X-ray astronomy, XRPIX6E, equipped with pinned depleted diode structure. *NIMA* **924**, 468–472 (2019).
- [15] Hagino, K. *et al.* Single event tolerance of x-ray siliconon-insulator pixel sensors. J. Astron. Telesc., Instrum., Syst. 8, 046001–046001 (2022).
- [16] Mori, K. *et al.* Total ionizing dose effects on the SOI pixel sensor for X-ray astronomical use. *NIMA* **924**, 473–479 (2019).
- [17] Hayashida, M. *et al.* Proton radiation hardness of x-ray SOI pixel sensors with pinned depleted diode structure. *JATIS* 7, 036001 (2021).
- [18] Takeda, A. *et al.* Development of on-chip pattern processing in event-driven SOI pixel detector for X-ray astronomy with background rejection purpose. *JINST* 15, P12025–P12025 (2020).
- [19] Matsuhashi, H. et al. Evaluation of the X-ray SOI pixel detector with the on-chip ADC. Nucl. Instrum. Methods Phys. Res. Sect. A: Accel., Spectrometers, Detect. Assoc. Equip. 1064, 169426 (2024).
- [20] Shimazoe, K. *et al.* Electron Pattern Recognition using trigger mode SOI pixel sensor for Advanced Compton Imaging. *JINST* 11, C02030–C02030 (2016).
- [21] Kagaya, M. et al. Evaluating the capability of detecting recoil-electron tracks using an electron-tracking Compton camera with a silicon-on-insulator pixel sensor. Nucl. Instrum. Methods Phys. Res. Sect. A: Accel., Spectrometers, Detect. Assoc. Equip. 1062, 169213 (2024).
- [22] Hashizume, M., Suda, Y., Fukazawa, Y., Tsuru, T. G. & Takeda, A. Performance evaluation of an event-driven silicon-on-insulator pixel detector "XRPIX8.5" for cosmic MeV gamma-ray observation. *Nucl. Instrum. Methods Phys. Res. Sect. A: Accel., Spectrometers, Detect. Assoc. Equip.* 169911 (2024) doi:10.1016/j.nima.2024.169911.
- [23] Onuki, Y. *et al.* Studies of radioactive background in SOI pixel detector for solar axion search experiment. *NIMA* 924, 448–451 (2019).









by using N-type wafer with >10k $\Omega$ cm so that we obtain high QE at both of high and low energy bands.

• adopted on-chip Al coating to block optical light

 mitigated radiation damage effect by adopting the charge Injection and cooling down to -120°C by using Stirling cooler



## X-ray astronomy discovered

- 1. There are a large number of black holes in the universe.
- 2. The universe is filled with high-temperature plasma reaching 100 million degree K.











Target Specification of the Device	
Imaging	pixel ~ 36µm□ same performance as CCD area: Req. ~15x22mm <sup>2</sup> , Goal ~15x44mm <sup>2</sup> 3side-buttable
Energy Band	Req. I-40 keV, Goal 0.5-40 keV Backside Illumination Req. <Ιμm, Goal 0.Ιμm Full Depletion Req. >250μm
Spectroscopy	ΔE : Req. < 300eV, Goal < 140eV @ 6keV ENC: Req. <10e-, Goal < 3e- ← Most Difficult
Time Resolution	< 10µsec new features with X-ray SOIPIX
Max Count Rate	> 2kHz / sensor for observation of bright X-ray sources





## PDD (Pinned Depleted Diode) Structure



### Conventional Single SOI

- large n-well connected to the sense node to collect signal charge
- a large sense node capacitance (C<sub>sense</sub>)
   → not easy to achieve low readout noise
- causes capacitive coupling and interference between pixel circuit and sensor layer → degrade spectroscopy performance

#### Pinned Depleted Diode (Kamehama+18)

- pinned p-well is formed under the interface of insulator and sensor layers
- the pinned p-well suppresses
- interference between pixel circuit and sensor layers
  - dark current from the interface between the sensor and insulator layers
- small sense node capacitance ( $C_{sense}$ )  $\rightarrow$  easier to achieve low readout noise

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We successfully demonstrated 300 eV FWHM at 6 keV (the energy resolution requirement)
 The jumps in INL may be a issue for the X-ray energy calibration.
 For the 20 keV range, the jumps are effectively reduced to 1/4 by adopting the high gain output.
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